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(71) Applicant (for all designated States except US): ASM INTER-NATIONAL N.V. [NL/NL]; P.O. Box 100, NL-3720 AC Bilthoven (NL).

(72) Inventors: and

(75) Inventors/Applicants (for US only): KUZNETSOV, Vladimir Ivanovich [RU/NL]; Buenos Airesstraat 8, NL-2622 AX Delft (NL). OOSTERLAKEN, Theodorus, Gerardus, Maria [NL/NL]; Meent 4, NL-3421 GT Oudewater (NL), RID-DER, Christianus, Gerardus, Maria [NL/NL]; Esdoomlaan 19, NL-3828 BK Hoogland (NL). GRANNEMAN, Ernst, Hendrik, August [NL/NL]; Hoge Naardeweg 71 A, NL-1217 AD Hilversum (NL).

(74) Agent: JORRITSMA, Ruurd; Nederlandsch Octrooibureau, Scheveningesweg 82, P.O. Box 29720, NL-2502 LS The Hague (NL).

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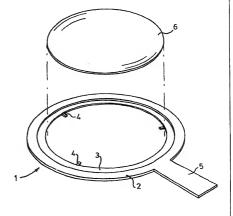
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(54) Title: METHOD FOR TRANSFERRING WAFERS AND RING

(57) Abstract

A method and installation are proposed with which a wafer is surrounded by a ring in a floating wafer reactor. This ring is used to restrict the change in temperature over the wafer, especially during introduction and removal. Moreover, such a ring can be used to position the wafer in the horizontal plane during the treatment. The wafer is not in contact with the ring during the treatment. The ring can optionally be provided with heating means.



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